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Embedded - FPGAs, or Field Programmable Gate Arrays, are advanced integrated circuits that offer unparalleled flexibility and performance for digital systems. Unlike traditional fixed-function logic devices, FPGAs can be programmed and reprogrammed to execute a wide array of logical operations, enabling customized functionality tailored to specific applications. This reprogrammability allows developers to iterate designs quickly and implement complex functions without the need for custom hardware.

Applications of Embedded - FPGAs

The versatility of Embedded - FPGAs makes them indispensable in numerous fields. In telecommunications.

Details	
Product Status	Obsolete
Number of LABs/CLBs	-
Number of Logic Elements/Cells	6000
Total RAM Bits	73728
Number of I/O	188
Number of Gates	-
Voltage - Supply	1.71V ~ 3.465V
Mounting Type	Surface Mount
Operating Temperature	-40°C ~ 100°C (TJ)
Package / Case	256-BGA
Supplier Device Package	256-FPBGA (17x17)
Purchase URL	https://www.e-xfl.com/product-detail/lattice-semiconductor/lfxp6c-4f256i

LatticeXP Family Data Sheet
Architecture

July 2007 Data Sheet DS1001

Architecture Overview

The LatticeXP architecture contains an array of logic blocks surrounded by Programmable I/O Cells (PIC). Interspersed between the rows of logic blocks are rows of sysMEM Embedded Block RAM (EBR) as shown in Figure 2-1.

On the left and right sides of the PFU array, there are Non-volatile Memory Blocks. In configuration mode this non-volatile memory is programmed via the IEEE 1149.1 TAP port or the sysCONFIG™ peripheral port. On power up, the configuration data is transferred from the Non-volatile Memory Blocks to the configuration SRAM. With this technology, expensive external configuration memories are not required and designs are secured from unauthorized read-back. This transfer of data from non-volatile memory to configuration SRAM via wide busses happens in microseconds, providing an “instant-on” capability that allows easy interfacing in many applications.

There are two kinds of logic blocks, the Programmable Functional Unit (PFU) and Programmable Functional unit without RAM/ROM (PFF). The PFU contains the building blocks for logic, arithmetic, RAM, ROM and register functions. The PFF block contains building blocks for logic, arithmetic and ROM functions. Both PFU and PFF blocks are optimized for flexibility, allowing complex designs to be implemented quickly and efficiently. Logic Blocks are arranged in a two-dimensional array. Only one type of block is used per row. The PFU blocks are used on the outside rows. The rest of the core consists of rows of PFF blocks interspersed with rows of PFU blocks. For every three rows of PFF blocks there is a row of PFU blocks.

Each PIC block encompasses two PIOs (PIO pairs) with their respective sysIO interfaces. PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs. sysMEM EBRs are large dedicated fast memory blocks. They can be configured as RAM or ROM.

The PFU, PFF, PIC and EBR Blocks are arranged in a two-dimensional grid with rows and columns as shown in Figure 2-1. The blocks are connected with many vertical and horizontal routing channel resources. The place and route software tool automatically allocates these routing resources.

At the end of the rows containing the sysMEM Blocks are the sysCLOCK Phase Locked Loop (PLL) Blocks. These PLLs have multiply, divide and phase shifting capability; they are used to manage the phase relationship of the clocks. The LatticeXP architecture provides up to four PLLs per device.

Every device in the family has a JTAG Port with internal Logic Analyzer (ispTRACY) capability. The sysCONFIG port which allows for serial or parallel device configuration. The LatticeXP devices are available for operation from 3.3V, 2.5V, 1.8V and 1.2V power supplies, providing easy integration into the overall system.

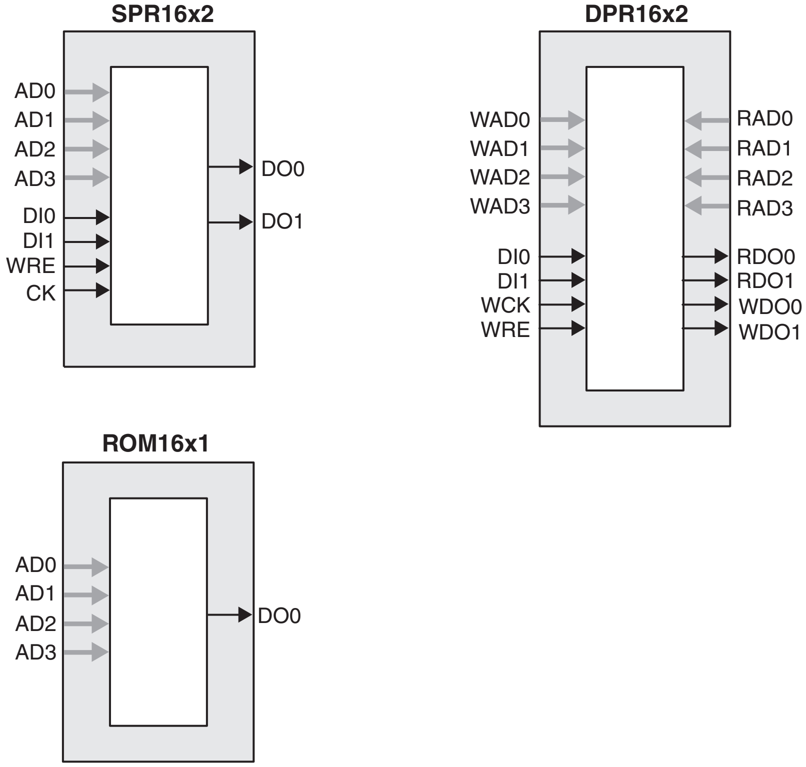
The Lattice design tools support the creation of a variety of different size memories. Where appropriate, the software will construct these using distributed memory primitives that represent the capabilities of the PFU. Table 2-3 shows the number of Slices required to implement different distributed RAM primitives. Figure 2-4 shows the distributed memory primitive block diagrams. Dual port memories involve the pairing of two Slices, one Slice functions as the read-write port. The other companion Slice supports the read-only port. For more information on RAM mode in LatticeXP devices, please see details of additional technical documentation at the end of this data sheet.

Table 2-3. Number of Slices Required for Implementing Distributed RAM

	SPR16x2	**DPR16x2**
Number of Slices	1	2

Note: SPR = Single Port RAM, DPR = Dual Port RAM

Figure 2-4. Distributed Memory Primitives



ROM Mode: The ROM mode uses the same principal as the RAM modes, but without the Write port. Pre-loading is accomplished through the programming interface during configuration.

PFU Modes of Operation

Slices can be combined within a PFU to form larger functions. Table 2-4 tabulates these modes and documents the functionality possible at the PFU level.

Figure 2-8. Per Quadrant Secondary Clock Selection

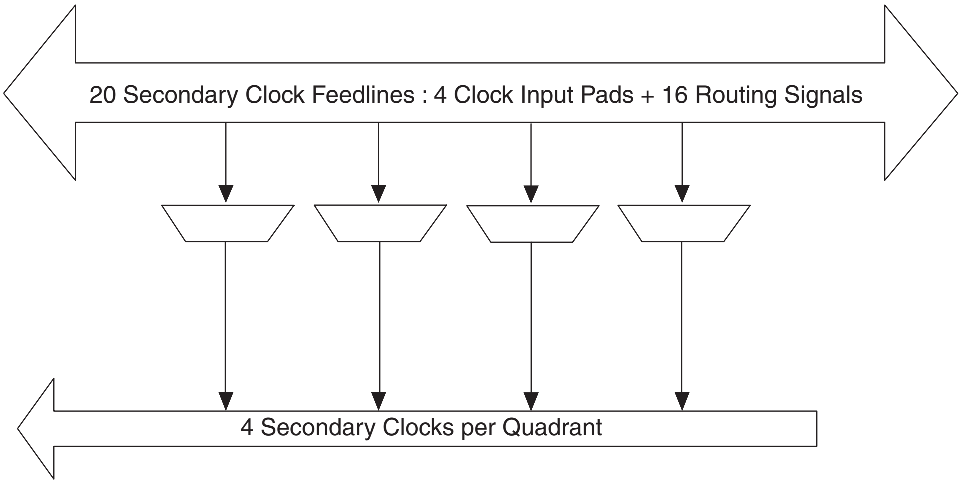
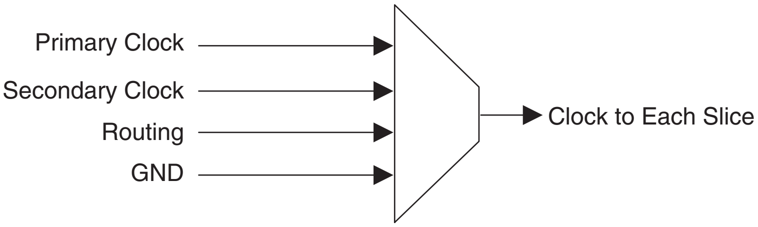


Figure 2-9. Slice Clock Selection



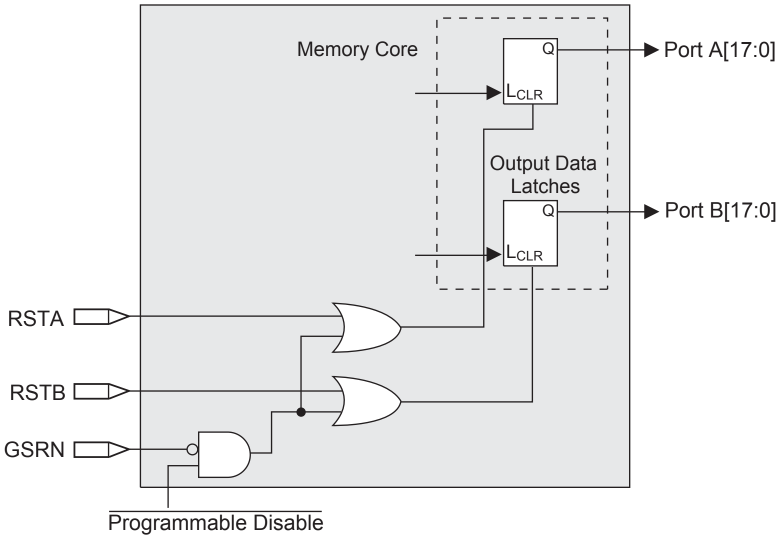
sysCLOCK Phase Locked Loops (PLLs)

The PLL clock input, from pin or routing, feeds into an input clock divider. There are three sources of feedback signals to the feedback divider: from CLKOP (PLL internal), from clock net (CLKOP or CLKOS) or from a user clock (PIN or logic). There is a PLL_LOCK signal to indicate that VCO has locked on to the input clock signal. Figure 2-10 shows the sysCLOCK PLL diagram.

The setup and hold times of the device can be improved by programming a delay in the feedback or input path of the PLL which will advance or delay the output clock with reference to the input clock. This delay can be either programmed during configuration or can be adjusted dynamically. In dynamic mode, the PLL may lose lock after adjustment and not relock until the t_{LOCK} parameter has been satisfied. Additionally, the phase and duty cycle block allows the user to adjust the phase and duty cycle of the CLKOS output.

The sysCLOCK PLLs provide the ability to synthesize clock frequencies. Each PLL has four dividers associated with it: input clock divider, feedback divider, post scalar divider and secondary clock divider. The input clock divider is used to divide the input clock signal, while the feedback divider is used to multiply the input clock signal. The post scalar divider allows the VCO to operate at higher frequencies than the clock output, thereby increasing the frequency range. The secondary divider is used to derive lower frequency outputs.

Figure 2-15. Memory Core Reset

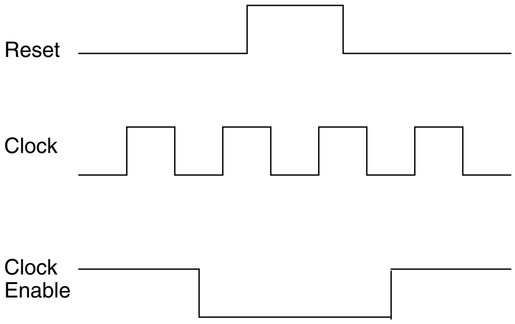


For further information on sysMEM EBR block, see the details of additional technical documentation at the end of this data sheet.

EBR Asynchronous Reset

EBR asynchronous reset or GSR (if used) can only be applied if all clock enables are low for a clock cycle before the reset is applied and released a clock cycle after the reset is released, as shown in Figure 2-16. The GSR input to the EBR is always asynchronous.

Figure 2-16. EBR Asynchronous Reset (Including GSR) Timing Diagram



If all clock enables remain enabled, the EBR asynchronous reset or GSR may only be applied and released after the EBR read and write clock inputs are in a steady state condition for a minimum of $1/f_{MAX}$ (EBR clock). The reset release must adhere to the EBR synchronous reset setup time before the next active read or write clock edge.

If an EBR is pre-loaded during configuration, the GSR input must be disabled or the release of the GSR during device Wake Up must occur before the release of the device I/Os becoming active.

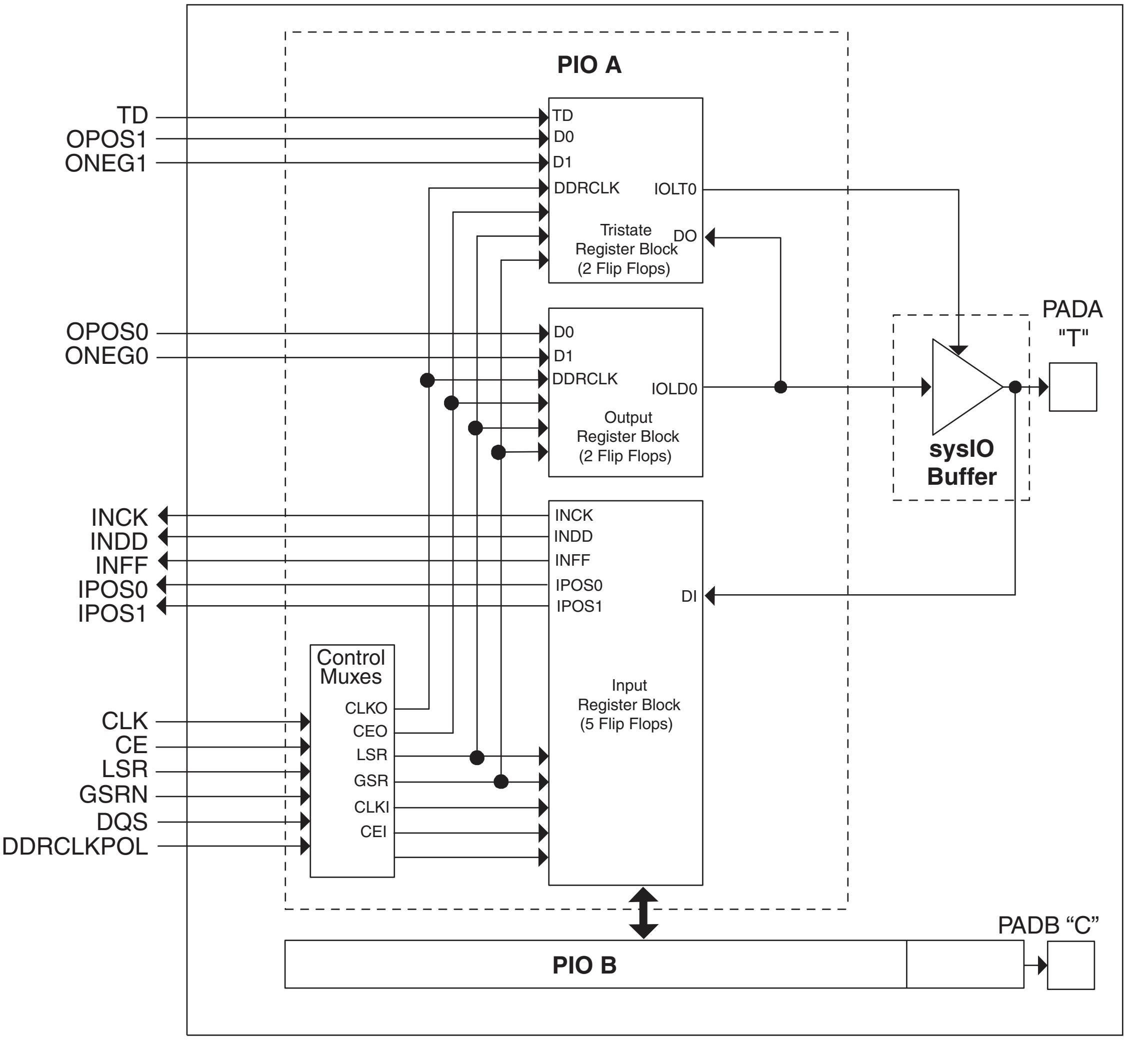
These instructions apply to all EBR RAM and ROM implementations.

Note that there are no reset restrictions if the EBR synchronous reset is used and the EBR GSR input is disabled.

Programmable I/O Cells (PICs)

Each PIC contains two PIOs connected to their respective sysIO Buffers which are then connected to the PADs as shown in Figure 2-17. The PIO Block supplies the output data (DO) and the Tri-state control signal (TO) to sysIO buffer, and receives input from the buffer.

Figure 2-17. PIC Diagram



In the LatticeXP family, seven PIOs or four (3.5) PICs are grouped together to provide two LVDS differential pairs, one PIC pair and one single I/O, as shown in Figure 2-18.

Two adjacent PIOs can be joined to provide a differential I/O pair (labeled as “T” and “C”). The PAD Labels “T” and “C” distinguish the two PIOs. Only the PIO pairs on the left and right edges of the device can be configured as LVDS transmit/receive pairs.

One of every 14 PIOs (a group of 8 PICs) contains a delay element to facilitate the generation of DQS signals as shown in Figure 2-19. The DQS signal feeds the DQS bus which spans the set of 13 PIOs (8 PICs). The DQS signal from the bus is used to strobe the DDR data from the memory into input register blocks. This interface is designed for memories that support one DQS strobe per eight bits of data.

The exact DQS pins are shown in a dual function in the Logic Signal Connections table in this data sheet. Additional detail is provided in the Signal Descriptions table in this data sheet.

Table 2-8. Supported Output Standards

Output Standard	Drive	V_{CCIO} (Nom.)
Single-ended Interfaces		
LVTTL	4mA, 8mA, 12mA, 16mA, 20mA	3.3
LVCMOS33	4mA, 8mA, 12mA 16mA, 20mA	3.3
LVCMOS25	4mA, 8mA, 12mA 16mA, 20mA	2.5
LVCMOS18	4mA, 8mA, 12mA 16mA	1.8
LVCMOS15	4mA, 8mA	1.5
LVCMOS12	2mA, 6mA	1.2
LVCMOS33, Open Drain	4mA, 8mA, 12mA 16mA, 20mA	—
LVCMOS25, Open Drain	4mA, 8mA, 12mA 16mA, 20mA	—
LVCMOS18, Open Drain	4mA, 8mA, 12mA 16mA	—
LVCMOS15, Open Drain	4mA, 8mA	—
LVCMOS12, Open Drain	2mA. 6mA	—
PCI33	N/A	3.3
HSTL18 Class I, II, III	N/A	1.8
HSTL15 Class I, III	N/A	1.5
SSTL3 Class I, II	N/A	3.3
SSTL2 Class I, II	N/A	2.5
SSTL18 Class I	N/A	1.8
Differential Interfaces		
Differential SSTL3, Class I, II	N/A	3.3
Differential SSTL2, Class I, II	N/A	2.5
Differential SSTL18, Class I	N/A	1.8
Differential HSTL18, Class I, II, III	N/A	1.8
Differential HSTL15, Class I, III	N/A	1.5
LVDS	N/A	2.5
BLVDS[1]	N/A	2.5
LVPECL[1]	N/A	3.3

1. Emulated with external resistors.

Hot Socketing

The LatticeXP devices have been carefully designed to ensure predictable behavior during power-up and power-down. Power supplies can be sequenced in any order. During power up and power-down sequences, the I/Os remain in tristate until the power supply voltage is high enough to ensure reliable operation. In addition, leakage into I/O pins is controlled to within specified limits, which allows easy integration with the rest of the system. These capabilities make the LatticeXP ideal for many multiple power supply and hot-swap applications.

Sleep Mode

The LatticeXP “C” devices (V_{CC} = 1.8/2.5/3.3V) have a sleep mode that allows standby current to be reduced by up to three orders of magnitude during periods of system inactivity. Entry and exit to Sleep Mode is controlled by the SLEEPN pin.

During Sleep Mode, the FPGA logic is non-operational, registers and EBR contents are not maintained and I/Os are tri-stated. Do not enter Sleep Mode during device programming or configuration operation. In Sleep Mode, power supplies can be maintained in their normal operating range, eliminating the need for external switching of power supplies. Table 2-9 compares the characteristics of Normal, Off and Sleep Modes.

sysIO Single-Ended DC Electrical Characteristics

Input/Output Standard	V_{IL}		V_{IH}		V_{OL} Max. (V)	V_{OH} Min. (V)	I_{OL} (mA)	I_{OH} (mA)
	Min. (V)	Max. (V)	Min. (V)	Max. (V)				
LVCMOS 3.3	-0.3	0.8	2.0	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVTTL	-0.3	0.8	2.0	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 2.5	-0.3	0.7	1.7	3.6	0.4	$V_{CCIO} - 0.4$	20, 16, 12, 8, 4	-20, -16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.8	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	$V_{CCIO} - 0.4$	16, 12, 8, 4	-16, -12, -8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.5	-0.3	$0.35V_{CCIO}$	$0.65V_{CCIO}$	3.6	0.4	$V_{CCIO} - 0.4$	8, 4	-8, -4
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.2 (“C” Version)	-0.3	0.42	0.78	3.6	0.4	$V_{CCIO} - 0.4$	6, 2	-6, -2
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
LVCMOS 1.2 (“E” Version)	-0.3	$0.35V_{CC}$	$0.65V_{CC}$	3.6	0.4	$V_{CCIO} - 0.4$	6, 2	-6, -2
					0.2	$V_{CCIO} - 0.2$	0.1	-0.1
PCI	-0.3	$0.3V_{CCIO}$	$0.5V_{CCIO}$	3.6	$0.1V_{CCIO}$	$0.9V_{CCIO}$	1.5	-0.5
SSTL3 class I	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.7	$V_{CCIO} - 1.1$	8	-8
SSTL3 class II	-0.3	$V_{REF} - 0.2$	$V_{REF} + 0.2$	3.6	0.5	$V_{CCIO} - 0.9$	16	-16
SSTL2 class I	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	3.6	0.54	$V_{CCIO} - 0.62$	7.6	-7.6
SSTL2 class II	-0.3	$V_{REF} - 0.18$	$V_{REF} + 0.18$	3.6	0.35	$V_{CCIO} - 0.43$	15.2	-15.2
SSTL18 class I	-0.3	$V_{REF} - 0.125$	$V_{REF} + 0.125$	3.6	0.4	$V_{CCIO} - 0.4$	6.7	-6.7
HSTL15 class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	8	-8
HSTL15 class III	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	24	-8
HSTL18 class I	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	9.6	-9.6
HSTL18 class II	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	16	-16
HSTL18 class III	-0.3	$V_{REF} - 0.1$	$V_{REF} + 0.1$	3.6	0.4	$V_{CCIO} - 0.4$	24	-8

1. The average DC current drawn by I/Os between GND connections, or between the last GND in an I/O bank and the end of an I/O bank, as shown in the logic signal connections table shall not exceed n * 8mA. Where n is the number of I/Os between bank GND connections or between the last GND in a bank and the end of a bank.

Timing Diagrams

PFU Timing Diagrams

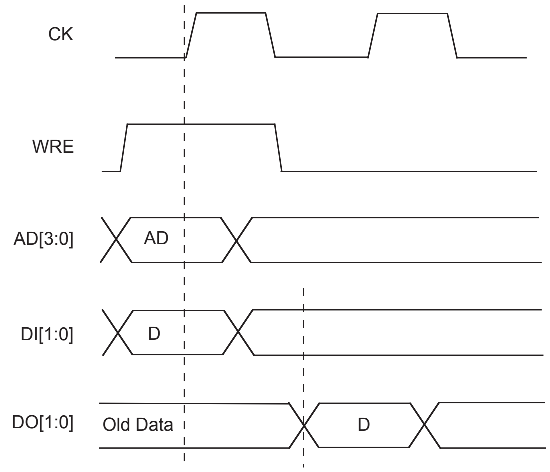


Figure 3-6. Slice Single/Dual Port Write Cycle Timing

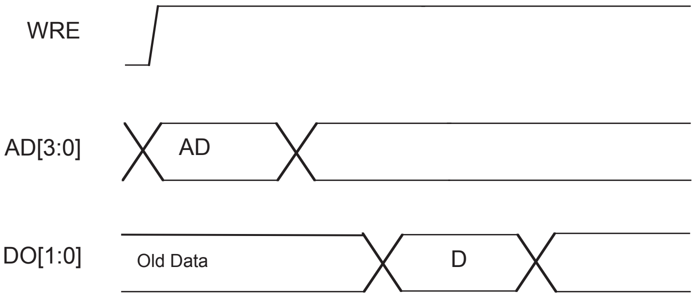


Figure 3-7. Slice Single /Dual Port Read Cycle Timing

Switching Test Conditions

Figure 3-13 shows the output test load that is used for AC testing. The specific values for resistance, capacitance, voltage, and other test conditions are shown in Figure 3-5.

Figure 3-13. Output Test Load, LVTTL and LVCMOS Standards

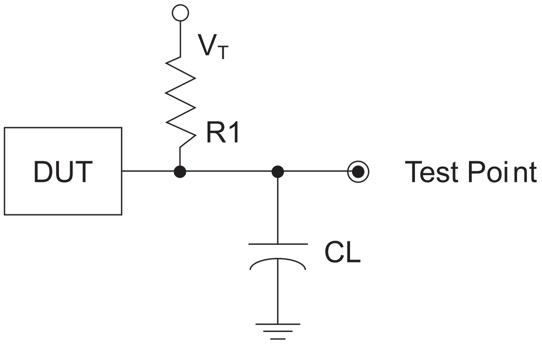


Table 3-5. Test Fixture Required Components, Non-Terminated Interfaces

Test Condition	R_1	C_L	Timing Ref.	V_T
LVTTL and other LVCMOS settings (L -> H, H -> L)	∞	0pF	LVCMOS 3.3 = 1.5V	—
			LVCMOS 2.5 = $V_{CCIO}/2$	—
			LVCMOS 1.8 = $V_{CCIO}/2$	—
			LVCMOS 1.5 = $V_{CCIO}/2$	—
			LVCMOS 1.2 = $V_{CCIO}/2$	—
LVCMOS 2.5 I/O (Z -> H)	188	0pF	$V_{CCIO}/2$	V_{OL}
LVCMOS 2.5 I/O (Z -> L)			$V_{CCIO}/2$	V_{OH}
LVCMOS 2.5 I/O (H -> Z)			V_{OH} - 0.15	V_{OL}
LVCMOS 2.5 I/O (L -> Z)			V_{OL} + 0.15	V_{OH}

Note: Output test conditions for all other interfaces are determined by the respective standards.

Signal Descriptions (Cont.)

Signal Name	I/O	Descriptions
Test and Programming (Dedicated pins. Pull-up is enabled on input pins during configuration.)		
TMS	I	Test Mode Select input, used to control the 1149.1 state machine.
TCK	I	Test Clock input pin, used to clock the 1149.1 state machine.
TDI	I	Test Data in pin, used to load data into device using 1149.1 state machine. After power-up, this TAP port can be activated for configuration by sending appropriate command. (Note: once a configuration port is selected it is locked. Another configuration port cannot be selected until the power-up sequence).
TDO	O	Output pin -Test Data out pin used to shift data out of device using 1149.1.
V_{CCJ}	—	V_{CCJ} - The power supply pin for JTAG Test Access Port.
Configuration Pads (used during sysCONFIG)		
CFG[1:0]	I	Mode pins used to specify configuration modes values latched on rising edge of INITN. During configuration, a pull-up is enabled.
INITN	I/O	Open Drain pin - Indicates the FPGA is ready to be configured. During configuration, a pull-up is enabled. If CFG1 and CFG0 are high (SDM) then this pin is pulled low.
PROGRAMN	I	Initiates configuration sequence when asserted low. This pin always has an active pull-up.
DONE	I/O	Open Drain pin - Indicates that the configuration sequence is complete, and the startup sequence is in progress.
CCLK	I/O	Configuration Clock for configuring an FPGA in sysCONFIG mode.
BUSY	I/O	Generally not used. After configuration it is a user-programmable I/O pin.
CSN	I	sysCONFIG chip select (Active low). During configuration, a pull-up is enabled. After configuration it is user a programmable I/O pin.
CS1N	I	sysCONFIG chip select (Active Low). During configuration, a pull-up is enabled. After configuration it is user programmable I/O pin
WRITEN	I	Write Data on Parallel port (Active low). After configuration it is a user programmable I/O pin
D[7:0]	I/O	sysCONFIG Port Data I/O. After configuration these are user programmable I/O pins.
DOUT, CSON	O	Output for serial configuration data (rising edge of CCLK) when using sysCONFIG port. After configuration, it is a user-programmable I/O pin.
DI	I	Input for serial configuration data (clocked with CCLK) when using sysCONFIG port. During configuration, a pull-up is enabled. After configuration it is a user-programmable I/O pin.
SLEEPN[2]	I	Sleep Mode pin - Active low sleep pin.þ When this pin is held high, the device operates normally.þ When driven low, the device moves into Sleep Mode after a specified time.This pin has a weak internal pull-up, but when not used an external pull-up to V_{CC} is recommended.
TOE[3]	I	Test Output Enable tri-states all I/O pins when driven low. This pin has a weak internal pull-up, but when not used an external pull-up to V_{CC} is recommended.

1. Applies toþ LFXP10, LFXP15 and LFXP20 only.
2. Applies to LFXP “C” devices only.
3. Applies to LFXP “E” devices only.

LFXP3 Logic Signal Connections: 100 TQFP (Cont.)

Pin Number	Pin Function	Bank	Differential	Dual Function
88	PT14B	1	-	D7
89	PT13B	0	C	BUSY
90	GNDIO0	0	-	-
91	PT13A	0	T	CS1N
92	PT12B	0	C	PCLKC0_0
93	PT12A	0	T	PCLKT0_0
94	VCCIO0	0	-	-
95	PT9A	0	-	DOUT
96	PT8A	0	-	WRITEN
97	PT6A	0	-	DI
98	PT5A	0	-	CSN
99	GND	-	-	-
100	CFG0	0	-	-

1. Applies to LFXP “C” only.
2. Applies to LFXP “E” only.
3. Supports dedicated LVDS outputs.

LFXP3 & LFXP6 Logic Signal Connections: 208 PQFP (Cont.)

Pin Number	LFXP3				LFXP6			
	Pin Function	Bank	Differential	Dual Function	Pin Function	Bank	Differential	Dual Function
93	PB19B	4	C	VREF1_4	PB22B	4	C	VREF1_4
94	PB20A	4	T	-	PB23A	4	T	-
95	PB20B	4	C	-	PB23B	4	C	-
96	PB21A	4	T	-	PB24A	4	T	-
97	VCCIO4	4	-	-	VCCIO4	4	-	-
98	PB21B	4	C	-	PB24B	4	C	-
99	PB22A	4	T	-	PB25A	4	T	-
100	PB22B	4	C	-	PB25B	4	C	-
101	PB23A	4	T	-	PB26A	4	T	-
102	PB23B	4	C	-	PB26B	4	C	-
103	PB24A	4	T	VREF2_4	PB27A	4	-	VREF2_4
104	PB24B	4	C	-	PB30A	4	T	DQS
105	PB25A	4	-	-	PB30B	4	C	-
106	GND	-	-	-	GND	-	-	-
107	VCC	-	-	-	VCC	-	-	-
108	PR18B	3	C[3]	-	PR26B	3	C[3]	-
109	GNDIO3	3	-	-	GNDIO3	3	-	-
110	PR18A	3	T[3]	-	PR26A	3	T[3]	-
111	PR17B	3	C	-	PR25B	3	C	-
112	PR17A	3	T	-	PR25A	3	T	-
113	PR16B	3	C[3]	-	PR24B	3	C[3]	-
114	PR16A	3	T[3]	DQS	PR24A	3	T[3]	DQS
115	VCCIO3	3	-	-	VCCIO3	3	-	-
116	PR15B	3	-	VREF1_3	PR23B	3	-	VREF1_3
117	PR14A	3	-	VREF2_3	PR22A	3	-	VREF2_3
118	GNDIO3	3	-	-	GNDIO3	3	-	-
119	PR13B	3	C	-	PR21B	3	C[3]	-
120	PR13A	3	T	-	PR21A	3	T[3]	-
121	GND	-	-	-	GND	-	-	-
122	PR12B	3	C	-	PR20B	3	C	-
123	PR12A	3	T	-	PR20A	3	T	-
124	PR11B	3	C	-	PR19B	3	C[3]	-
125	VCCIO3	3	-	-	VCCIO3	3	-	-
126	PR11A	3	T	-	PR19A	3	T[3]	-
127	GNDP1	-	-	-	GNDP1	-	-	-
128	VCCP1	-	-	-	VCCP1	-	-	-
129	NC	-	-	-	PR13A	2	-	-
130	GND	-	-	-	GND	-	-	-
131	PR9B	2	C	PCLKC2_0	PR12B	2	C	PCLKC2_0
132	PR9A	2	T	PCLKT2_0	PR12A	2	T	PCLKT2_0
133	NC	-	-	-	PR11B	2	C[3]	-
134	NC	-	-	-	PR11A	2	T[3]	-
135	GNDIO2	2	-	-	GNDIO2	2	-	-
136	PR8B	2	C	RUM0_PLLC_IN_A	PR8B	2	C	RUM0_PLLC_IN_A
137	PR8A	2	T	RUM0_PLLT_IN_A	PR8A	2	T	RUM0_PLLT_IN_A
138	PR7B	2	C[3]	-	PR7B	2	C[3]	-

LFXP6 & LFXP10 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP6				LFXP10			
Ball Number	**Ball Function**	**Bank**	**Differential**	**Dual Function**	**Ball Function**	**Bank**	**Differential**	**Dual Function**
R8	PB16A	5	T	-	PB20A	5	T	-
T9	PB16B	5	C	-	PB20B	5	C	-
R9	PB17A	4	T	-	PB21A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
P9	PB17B	4	C	-	PB21B	4	C	-
T10	PB18A	4	T	PCLKT4_0	PB22A	4	T	PCLKT4_0
T11	PB18B	4	C	PCLKC4_0	PB22B	4	C	PCLKC4_0
R10	PB19A	4	T	-	PB23A	4	T	-
P10	PB19B	4	C	-	PB23B	4	C	-
N9	PB20A	4	-	-	PB24A	4	-	-
M9	PB21B	4	-	-	PB25B	4	-	-
R12	PB22A	4	T	DQS	PB26A	4	T	DQS
-	GNDIO4	4	-	-	GNDIO4	4	-	-
T12	PB22B	4	C	VREF1_4	PB26B	4	C	VREF1_4
P13	PB23A	4	T	-	PB27A	4	T	-
R13	PB23B	4	C	-	PB27B	4	C	-
M11	PB24A	4	T	-	PB28A	4	T	-
N11	PB24B	4	C	-	PB28B	4	C	-
N10	PB25A	4	T	-	PB29A	4	T	-
M10	PB25B	4	C	-	PB29B	4	C	-
T13	PB26A	4	T	-	PB30A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
P14	PB26B	4	C	-	PB30B	4	C	-
R11	PB27A	4	T	VREF2_4	PB31A	4	T	VREF2_4
P12	PB27B	4	C	-	PB31B	4	C	-
T14	PB28A	4	-	-	PB32A	4	-	-
R14	PB29B	4	-	-	PB33B	4	-	-
P11	PB30A	4	T	DQS	PB34A	4	T	DQS
N12	PB30B	4	C	-	PB34B	4	C	-
T15	PB31A	4	T	-	PB35A	4	T	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
R15	PB31B	4	C	-	PB35B	4	C	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
P15	PR26B	3	C[3]	-	PR34B	3	C	RLM0_PLLC_FB_A
N15	PR26A	3	T[3]	-	PR34A	3	T	RLM0_PLLT_FB_A
P16	PR24B	3	C[3]	-	PR33B	3	C[3]	-
R16	PR24A	3	T[3]	DQS	PR33A	3	T[3]	DQS
M15	PR15B	3	-	-	PR32B	3	-	-
N14	PR23B	3	-	VREF1_3	PR31A	3	-	VREF1_3
-	GNDIO3	3	-	-	GNDIO3	3	-	-
M14	PR25B	3	C	-	PR29B	3	C	-
L13	PR25A	3	T	-	PR29A	3	T	-

LFXP15 & LFXP20 Logic Signal Connections: 256 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
P16	PR37B	3	C^3	-	PR41B	3	C^3	-
R16	PR37A	3	T^3	DQS	PR41A	3	T^3	DQS
M15	PR36B	3	-	-	PR40B	3	-	-
N14	PR35A	3	-	VREF1_3	PR39A	3	-	VREF1_3
-	GNDIO3	3	-	-	GNDIO3	3	-	-
M14	PR33B	3	C	-	PR37B	3	C	-
L13	PR33A	3	T	-	PR37A	3	T	-
L15	PR32B	3	C^3	-	PR36B	3	C^3	-
L14	PR32A	3	T^3	-	PR36A	3	T^3	-
L12	PR30A	3	-	-	PR34A	3	-	-
M16	PR29B	3	C	RLM0_PLLC_IN_A	PR33B	3	C	RLM0_PLLC_IN_A
N16	PR29A	3	T	RLM0_PLLT_IN_A	PR33A	3	T	RLM0_PLLT_IN_A
-	GNDIO3	3	-	-	GNDIO3	3	-	-
K14	PR28B	3	C^3	-	PR32B	3	C^3	-
K15	PR28A	3	T^3	DQS	PR32A	3	T^3	DQS
K12	PR27B	3	-	-	PR31B	3	-	-
K13	PR26A	3	-	VREF2_3	PR30A	3	-	VREF2_3
L16	PR25B	3	C^3	-	PR29B	3	C^3	-
K16	PR25A	3	T^3	-	PR29A	3	T^3	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
J15	PR23B	3	C^3	-	PR27B	3	C^3	-
J14	PR23A	3	T^3	-	PR27A	3	T^3	-
J13	GNDP1	-	-	-	GNDP1	-	-	-
J12	VCCP1	-	-	-	VCCP1	-	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
J16	PR21B	2	C	PCLKC2_0	PR21B	2	C	PCLKC2_0
H16	PR21A	2	T	PCLKT2_0	PR21A	2	T	PCLKT2_0
H13	PR20B	2	C^3	-	PR20B	2	C^3	-
H12	PR20A	2	T^3	DQS	PR20A	2	T^3	DQS
H15	PR19B	2	-	-	PR19B	2	-	-
H14	PR18A	2	-	VREF1_2	PR18A	2	-	VREF1_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G15	PR17B	2	C^3	-	PR17B	2	C^3	-
G14	PR17A	2	T^3	-	PR17A	2	T^3	-
G16	PR16B	2	C	RUM0_PLLC_IN_A	PR16B	2	C	RUM0_PLLC_IN_A
F16	PR16A	2	T	RUM0_PLLT_IN_A	PR16A	2	T	RUM0_PLLT_IN_A
G13	PR15B	2	-	-	PR15B	2	-	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
G12	PR12B	2	C	-	PR12B	2	C	-
F13	PR12A	2	T	-	PR12A	2	T	-
B16	PR11B	2	C^3	-	PR11B	2	C^3	-
C16	PR11A	2	T^3	DQS	PR11A	2	T^3	DQS

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
T6	PL41A	6	T	-	PL45A	6	T	-
T5	PL41B	6	C	-	PL45B	6	C	-
-	GNDIO6	6	-	-	GNDIO6	6	-	-
U3	PL42A	6	T[3]	-	PL46A	6	T[3]	-
U4	PL42B	6	C[3]	-	PL46B	6	C[3]	-
V4	PL43A	6	-	-	PL47A	6	-	-
W4	SLEEPN[1]/ TOE[2]	-	-	-	SLEEPN[1]/ TOE[2]	-	-	-
W5	INITN	5	-	-	INITN	5	-	-
Y3	-	-	-	-	PB3B	5	-	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
U5	-	-	-	-	PB4A	5	T	-
V5	-	-	-	-	PB4B	5	C	-
Y4	-	-	-	-	PB5A	5	T	-
Y5	-	-	-	-	PB5B	5	C	-
V6	-	-	-	-	PB6A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
U6	-	-	-	-	PB6B	5	C	-
W6	PB3A	5	T	-	PB7A	5	T	-
Y6	PB3B	5	C	-	PB7B	5	C	-
AA2	PB4A	5	T	-	PB8A	5	T	-
AA3	PB4B	5	C	-	PB8B	5	C	-
V7	PB5A	5	-	-	PB9A	5	-	-
U7	PB6B	5	-	-	PB10B	5	-	-
Y7	PB7A	5	T	DQS	PB11A	5	T	DQS
W7	PB7B	5	C	-	PB11B	5	C	-
AA4	PB8A	5	T	-	PB12A	5	T	-
-	GNDIO5	5	-	-	GNDIO5	5	-	-
AA5	PB8B	5	C	-	PB12B	5	C	-
AB3	PB9A	5	T	-	PB13A	5	T	-
AB4	PB9B	5	C	-	PB13B	5	C	-
AA6	PB10A	5	T	-	PB14A	5	T	-
AA7	PB10B	5	C	-	PB14B	5	C	-
U8	PB11A	5	T	-	PB15A	5	T	-
V8	PB11B	5	C	-	PB15B	5	C	-
Y8	PB12A	5	T	VREF1_5	PB16A	5	T	VREF1_5
-	GNDIO5	5	-	-	GNDIO5	5	-	-
W8	PB12B	5	C	-	PB16B	5	C	-
V9	PB13A	5	-	-	PB17A	5	-	-
U9	PB14B	5	-	-	PB18B	5	-	-
Y9	PB15A	5	T	DQS	PB19A	5	T	DQS
W9	PB15B	5	C	-	PB19B	5	C	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
AB19	PB37A	4	-	-	PB41A	4	-	-
AB20	PB38B	4	-	-	PB42B	4	-	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
V15	PB39A	4	T	DQS	PB43A	4	T	DQS
U15	PB39B	4	C	-	PB43B	4	C	-
Y15	PB40A	4	T	-	PB44A	4	T	-
W15	PB40B	4	C	-	PB44B	4	C	-
AA16	PB41A	4	T	-	PB45A	4	T	-
AA17	PB41B	4	C	-	PB45B	4	C	-
AA18	PB42A	4	T	-	PB46A	4	T	-
AA19	PB42B	4	C	-	PB46B	4	C	-
Y16	PB43A	4	T	-	PB47A	4	T	-
W16	PB43B	4	C	-	PB47B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
AA20	PB44A	4	T	-	PB48A	4	T	-
AA21	PB44B	4	C	-	PB48B	4	C	-
Y17	PB45A	4	-	-	PB49A	4	-	-
Y18	PB46B	4	-	-	PB50B	4	-	-
Y19	PB47A	4	T	DQS	PB51A	4	T	DQS
Y20	PB47B	4	C	-	PB51B	4	C	-
V16	PB48A	4	T	-	PB52A	4	T	-
U16	PB48B	4	C	-	PB52B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
U18	-	-	-	-	PB53A	4	T	-
V18	-	-	-	-	PB53B	4	C	-
W19	-	-	-	-	PB54A	4	T	-
W18	-	-	-	-	PB54B	4	C	-
U17	-	-	-	-	PB55A	4	T	-
V17	-	-	-	-	PB55B	4	C	-
-	GNDIO4	4	-	-	GNDIO4	4	-	-
W17	-	-	-	-	PB56A	4	-	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
V19	PR43A	3	-	-	PR47A	3	-	-
U20	PR42B	3	C[3]	-	PR46B	3	C[3]	-
U19	PR42A	3	T[3]	-	PR46A	3	T[3]	-
V20	PR41B	3	C	-	PR45B	3	C	-
W20	PR41A	3	T	-	PR45A	3	T	-
T17	PR40B	3	C[3]	-	PR44B	3	C[3]	-
T18	PR40A	3	T[3]	-	PR44A	3	T[3]	-
T19	PR39B	3	C[3]	-	PR43B	3	C[3]	-
T20	PR39A	3	T[3]	-	PR43A	3	T[3]	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
R18	PR38B	3	C	RLM0_PLLC_FB_A	PR42B	3	C	RLM0_PLLC_FB_A
R17	PR38A	3	T	RLM0_PLLT_FB_A	PR42A	3	T	RLM0_PLLT_FB_A
Y22	PR37B	3	C[3]	-	PR41B	3	C[3]	-
Y21	PR37A	3	T[3]	DQS	PR41A	3	T[3]	DQS
W22	PR36B	3	-	-	PR40B	3	-	-
W21	PR35A	3	-	VREF1_3	PR39A	3	-	VREF1_3
P17	PR34B	3	C[3]	-	PR38B	3	C[3]	-
P18	PR34A	3	T[3]	-	PR38A	3	T[3]	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
R19	PR33B	3	C	-	PR37B	3	C	-
R20	PR33A	3	T	-	PR37A	3	T	-
V22	PR32B	3	C[3]	-	PR36B	3	C[3]	-
V21	PR32A	3	T[3]	-	PR36A	3	T[3]	-
U22	PR30B	3	C[3]	-	PR34B	3	C[3]	-
U21	PR30A	3	T[3]	-	PR34A	3	T[3]	-
P19	PR29B	3	C	RLM0_PLLC_IN_A	PR33B	3	C	RLM0_PLLC_IN_A
P20	PR29A	3	T	RLM0_PLLT_IN_A	PR33A	3	T	RLM0_PLLT_IN_A
-	GNDIO3	3	-	-	GNDIO3	3	-	-
T22	PR28B	3	C[3]	-	PR32B	3	C[3]	-
T21	PR28A	3	T[3]	DQS	PR32A	3	T[3]	DQS
R22	PR27B	3	-	-	PR31B	3	-	-
R21	PR26A	3	-	VREF2_3	PR30A	3	-	VREF2_3
N19	PR25B	3	C[3]	-	PR29B	3	C[3]	-
N20	PR25A	3	T[3]	-	PR29A	3	T[3]	-
N18	PR24B	3	C	-	PR28B	3	C	-
M18	PR24A	3	T	-	PR28A	3	T	-
-	GNDIO3	3	-	-	GNDIO3	3	-	-
P22	PR23B	3	C[3]	-	PR27B	3	C[3]	-
P21	PR23A	3	T[3]	-	PR27A	3	T[3]	-
N22	-	-	-	-	PR26B	3	C[3]	-
N21	-	-	-	-	PR26A	3	T[3]	-
M19	-	-	-	-	PR25B	3	-	-
M20	GNDP1	-	-	-	GNDP1	-	-	-
L18	VCCP1	-	-	-	VCCP1	-	-	-
M21	-	-	-	-	PR24A	2	-	-
M22	PR22B	2	C[3]	-	PR23B	2	C[3]	-
L22	PR22A	2	T[3]	-	PR23A	2	T[3]	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
L19	-	-	-	-	PR22B	2	C[3]	-
L20	-	-	-	-	PR22A	2	T[3]	-
L21	PR21B	2	C	PCLKC2_0	PR21B	2	C	PCLKC2_0
K22	PR21A	2	T	PCLKT2_0	PR21A	2	T	PCLKT2_0

LFXP15 & LFXP20 Logic Signal Connections: 484 fpBGA (Cont.)

	LFXP15				LFXP20			
Ball Number	Ball Function	Bank	Differential	Dual Function	Ball Function	Bank	Differential	Dual Function
J21	PR20B	2	C[3]	-	PR20B	2	C[3]	-
J22	PR20A	2	T[3]	DQS	PR20A	2	T[3]	DQS
K18	PR19B	2	-	-	PR19B	2	-	-
K19	PR18A	2	-	VREF1_2	PR18A	2	-	VREF1_2
-	GNDIO2	2	-	-	GNDIO2	2	-	-
K21	PR17B	2	C[3]	-	PR17B	2	C[3]	-
K20	PR17A	2	T[3]	-	PR17A	2	T[3]	-
H21	PR16B	2	C	RUM0_PLLC_IN_A	PR16B	2	C	RUM0_PLLC_IN_A
H22	PR16A	2	T	RUM0_PLLT_IN_A	PR16A	2	T	RUM0_PLLT_IN_A
J20	PR15B	2	C[3]	-	PR15B	2	C[3]	-
J19	PR15A	2	T[3]	-	PR15A	2	T[3]	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
J17	PR13B	2	C[3]	-	PR13B	2	C[3]	-
J18	PR13A	2	T[3]	-	PR13A	2	T[3]	-
G21	PR12B	2	C	-	PR12B	2	C	-
G22	PR12A	2	T	-	PR12A	2	T	-
F21	PR11B	2	C[3]	-	PR11B	2	C[3]	-
F22	PR11A	2	T[3]	DQS	PR11A	2	T[3]	DQS
-	GNDIO2	2	-	-	GNDIO2	2	-	-
H20	PR10B	2	-	-	PR10B	2	-	-
H19	PR9A	2	-	VREF2_2	PR9A	2	-	VREF2_2
H17	PR8B	2	C[3]	-	PR8B	2	C[3]	-
H18	PR8A	2	T[3]	-	PR8A	2	T[3]	-
E21	PR7B	2	C	RUM0_PLLC_FB_A	PR7B	2	C	RUM0_PLLC_FB_A
E22	PR7A	2	T	RUM0_PLLT_FB_A	PR7A	2	T	RUM0_PLLT_FB_A
D21	PR6B	2	C[3]	-	PR6B	2	C[3]	-
D22	PR6A	2	T[3]	-	PR6A	2	T[3]	-
G20	PR5B	2	C[3]	-	PR5B	2	C[3]	-
G19	PR5A	2	T[3]	-	PR5A	2	T[3]	-
G17	PR4B	2	C	-	PR4B	2	C	-
G18	PR4A	2	T	-	PR4A	2	T	-
-	GNDIO2	2	-	-	GNDIO2	2	-	-
F18	PR3B	2	C[3]	-	PR3B	2	C[3]	-
F19	PR3A	2	T[3]	-	PR3A	2	T[3]	-
C22	PR2B	2	-	-	PR2B	2	-	-
F20	TDO	-	-	-	TDO	-	-	-
E20	VCCJ	-	-	-	VCCJ	-	-	-
D19	TDI	-	-	-	TDI	-	-	-
E19	TMS	-	-	-	TMS	-	-	-
D20	TCK	-	-	-	TCK	-	-	-
C20	-	-	-	-	PT56A	1	-	-
-	GNDIO1	1	-	-	GNDIO1	1	-	-

Conventional Packaging

Commercial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3C-3Q208C	136	1.8/2.5/3.3V	-3	PQFP	208	COM	3.1K
LFXP3C-4Q208C	136	1.8/2.5/3.3V	-4	PQFP	208	COM	3.1K
LFXP3C-5Q208C	136	1.8/2.5/3.3V	-5	PQFP	208	COM	3.1K
LFXP3C-3T144C	100	1.8/2.5/3.3V	-3	TQFP	144	COM	3.1K
LFXP3C-4T144C	100	1.8/2.5/3.3V	-4	TQFP	144	COM	3.1K
LFXP3C-5T144C	100	1.8/2.5/3.3V	-5	TQFP	144	COM	3.1K
LFXP3C-3T100C	62	1.8/2.5/3.3V	-3	TQFP	100	COM	3.1K
LFXP3C-4T100C	62	1.8/2.5/3.3V	-4	TQFP	100	COM	3.1K
LFXP3C-5T100C	62	1.8/2.5/3.3V	-5	TQFP	100	COM	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	5.8K
LFXP6C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	5.8K
LFXP6C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	5.8K
LFXP6C-3Q208C	142	1.8/2.5/3.3V	-3	PQFP	208	COM	5.8K
LFXP6C-4Q208C	142	1.8/2.5/3.3V	-4	PQFP	208	COM	5.8K
LFXP6C-5Q208C	142	1.8/2.5/3.3V	-5	PQFP	208	COM	5.8K
LFXP6C-3T144C	100	1.8/2.5/3.3V	-3	TQFP	144	COM	5.8K
LFXP6C-4T144C	100	1.8/2.5/3.3V	-4	TQFP	144	COM	5.8K
LFXP6C-5T144C	100	1.8/2.5/3.3V	-5	TQFP	144	COM	5.8K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP10C-3F388C	244	1.8/2.5/3.3V	-3	fpBGA	388	COM	9.7K
LFXP10C-4F388C	244	1.8/2.5/3.3V	-4	fpBGA	388	COM	9.7K
LFXP10C-5F388C	244	1.8/2.5/3.3V	-5	fpBGA	388	COM	9.7K
LFXP10C-3F256C	188	1.8/2.5/3.3V	-3	fpBGA	256	COM	9.7K
LFXP10C-4F256C	188	1.8/2.5/3.3V	-4	fpBGA	256	COM	9.7K
LFXP10C-5F256C	188	1.8/2.5/3.3V	-5	fpBGA	256	COM	9.7K

Commercial (Cont.)

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP15E-3FN484C	300	1.2V	-3	fpBGA	484	COM	15.5K
LFXP15E-4FN484C	300	1.2V	-4	fpBGA	484	COM	15.5K
LFXP15E-5FN484C	300	1.2V	-5	fpBGA	484	COM	15.5K
LFXP15E-3FN388C	268	1.2V	-3	fpBGA	388	COM	15.5K
LFXP15E-4FN388C	268	1.2V	-4	fpBGA	388	COM	15.5K
LFXP15E-5FN388C	268	1.2V	-5	fpBGA	388	COM	15.5K
LFXP15E-3FN256C	188	1.2V	-3	fpBGA	256	COM	15.5K
LFXP15E-4FN256C	188	1.2V	-4	fpBGA	256	COM	15.5K
LFXP15E-5FN256C	188	1.2V	-5	fpBGA	256	COM	15.5K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP20E-3FN484C	340	1.2V	-3	fpBGA	484	COM	19.7K
LFXP20E-4FN484C	340	1.2V	-4	fpBGA	484	COM	19.7K
LFXP20E-5FN484C	340	1.2V	-5	fpBGA	484	COM	19.7K
LFXP20E-3FN388C	268	1.2V	-3	fpBGA	388	COM	19.7K
LFXP20E-4FN388C	268	1.2V	-4	fpBGA	388	COM	19.7K
LFXP20E-5FN388C	268	1.2V	-5	fpBGA	388	COM	19.7K
LFXP20E-3FN256C	188	1.2V	-3	fpBGA	256	COM	19.7K
LFXP20E-4FN256C	188	1.2V	-4	fpBGA	256	COM	19.7K
LFXP20E-5FN256C	188	1.2V	-5	fpBGA	256	COM	19.7K

Industrial

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP3C-3QN208I	136	1.8/2.5/3.3V	-3	PQFP	208	IND	3.1K
LFXP3C-4QN208I	136	1.8/2.5/3.3V	-4	PQFP	208	IND	3.1K
LFXP3C-3TN144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	3.1K
LFXP3C-4TN144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	3.1K
LFXP3C-3TN100I	62	1.8/2.5/3.3V	-3	TQFP	100	IND	3.1K
LFXP3C-4TN100I	62	1.8/2.5/3.3V	-4	TQFP	100	IND	3.1K

Part Number	I/Os	Voltage	Grade	Package	Pins	Temp.	LUTs
LFXP6C-3FN256I	188	1.8/2.5/3.3V	-3	fpBGA	256	IND	5.8K
LFXP6C-4FN256I	188	1.8/2.5/3.3V	-4	fpBGA	256	IND	5.8K
LFXP6C-3QN208I	142	1.8/2.5/3.3V	-3	PQFP	208	IND	5.8K
LFXP6C-4QN208I	142	1.8/2.5/3.3V	-4	PQFP	208	IND	5.8K
LFXP6C-3TN144I	100	1.8/2.5/3.3V	-3	TQFP	144	IND	5.8K
LFXP6C-4TN144I	100	1.8/2.5/3.3V	-4	TQFP	144	IND	5.8K